

AMENDMENTS TO THE SPECIFICATION

- Please amend the Cross-Reference to Related Application(s) section, which begins on page 1, line 2, as follows:

CROSS-REFERENCE TO RELATED APPLICATION(S)

This is a divisional of co-pending application serial number 10/279,900 filed October 24, 2002, which is hereby incorporated by reference herein.

- Please replace the paragraph, which begins on page 2, line 13, with the following paragraph:

With the continuing decrease in the size of the contact pads that are used to connect pre-solder bumps thereto, the pitch of the solder bumps becomes increasingly more important. The invention addresses this issue and provides a method that significantly improves the pitch of the solder bumps that interface between a semiconductor device and the device supporting substrate over which the device is mounted.

- Please replace the paragraph, which begins on page 2, line 21, with the following paragraph:

A principle objective of the invention is to ~~increase~~ decrease the pitch of an array of solder bumps.

- Please replace the paragraph, which begins on page 2, line 28, with the following paragraph:

A still further objective of the invention is to provide a highly integratable and manufacturable method of creating solder bumps for a high-density, high performance flip chip package.

- Please replace the paragraph, which begins on page 4, line 1, with the following paragraph:

For reasons of comparison and improved understanding of the invention, comparable conventional methods of creating a solder bump are first highlighted using Figs. 1 and 2 for ~~the~~ this purpose.

- Please replace the paragraph, which begins on page 5, line 4, with the following paragraph:

The selection of the materials that are used for the various overlying layers ~~are~~ is determined by considerations of interlayer adhesion, metal diffusion, metal corrosion, issues of layer delamination and the like.

- Please replace the paragraph, which begins on page 6, line 30, with the following paragraph:

The preferred dry film of the invention is of a negative type photo-polymer. This results in surface areas of the layer of dry film that, ~~are~~ when exposed by G, H and I line UV light, will remain over the surface of the wafer while unexposed surface areas will be removed by applying for instant an alkaline solution to the surface thereof.

- Please amend the Abstract which begins on page 19, line 1, as follows which begins on the next page: